

2026 10th International Conference on Vision Image and Signal Processing

December 11-13, 2026 | Haikou, China

2026年第十届视觉、图像与信息信号处理国际会议

Welcome to ICVISIP 2026

It is with great pleasure that we invite you to the 2026 10th International Conference on Vision, Image and Signal Processing (ICVISIP 2026), which is organized by Hainan University, and is scheduled to take place from December 11-13, 2026, in Haikou, China.

ICVISIP is committed to delivering a platform for collaboration and discovery, with the aim of driving progress in image, vision, and signal processing—key technologies that are enhancing our understanding of the world and propelling advancements in artificial intelligence, machine learning, and a multitude of other applications that are transforming industries and improving lives.

We warmly invite your contributions and eagerly anticipate the opportunity to meet with you in person at ICVISIP 2026.

Organizing Committee

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Topics of Interest

For more information, please visit: www.icvisp.org/cfp.html

Computer Vision

- 3D Computer Vision
- Adversarial Attack and Defense

- Deep Learning Architectures and Techniques
- Document Analysis and Understanding

- Embodied Vision
- Low-level Vision

Image Processing

- Synthesis, Rendering, & Visualization
- Computational Imaging

- Restoration & Enhancement
- Image & Video Quality Models

- AI-Powered Image & Video Processing
- Medical Image Processing

Signal Processing

- Applied Signal Processing Systems
- Audio & Acoustic Signal Processing

- Biomedical Imaging & Signal Processing
- Compressive Sensing, Sparse Modeling

- Machine Learning and Generative AI
- Sensor Array & Multichannel SP

Multimodal AI

- Multimodal Data Modeling
- Multimodal Data Fusion

- Cross/Multi-modal Learning
- Multimodal Big Data Analytics and Visualization

- Multimodal Perception and Interaction
- Multimodal AI in Robotics

Applications

- Augmented and Mixed Reality
- Autonomous Driving

- Low-Altitude Visual Perception and Understanding
- Mental Health and Cognitive Stimulation

- Vision, Language, and Reasoning
- Vision Applications and Systems

Tracks

For more information, please visit: www.icvisp.org/tracks.html

Track I :

The Application of Artificial Intelligence in the Field of Meteorology

Track III:

Multi-Modal Perception and Affective Computing

Track II :

Advances in Hyperspectral Data Analysis and Processing

Track IV

Signal Analysis, Feature Extraction and Intelligent Recognition

Key Dates

Abstract Submission Due: August 1, 2026

Full Paper Submission Due: August 15, 2026

Author Notification Due: October 1, 2026

Registration Due: November 5, 2026

Camera-ready Submission Due: November 5, 2026

Main Conference: December 11-13, 2026

Publication

Registered and presented full papers will be included in the ICVISIP 2026 digital conference proceedings and submitted to major citation databases (including, but not limited to Ei Compendex and Scopus) for review and indexing.



Publication History

ICVISIP 2017 | Osaka, Japan

Published by IEEE

ISBN: 978-1-5386-0612-4

EI Compendex & Scopus

ICVISIP 2018 | Las Vegas, USA

Published by ACM

ISBN: 978-1-4503-6529-1

EI Compendex & Scopus

ICVISIP 2019 | University of British Columbia

Published by ACM

ISBN: 978-1-4503-7625-9

EI Compendex & Scopus

ICVISIP 2020 | Virtually

Published by ACM

ISBN: 978-1-4503-8953-2

EI Compendex & Scopus

ICVISIP 2021 | Virtually

Published by IEEE

ISBN: 978-1-6654-0770-0

EI Compendex & Scopus

ICVISIP 2022 | Virtually

Published by IOP JPCS

ISSN: 1742-6596

EI Compendex & Scopus

ICVISIP 2023 | Dali, China

Published by IET

ISBN: 978-1-83724-014-2

EI Compendex & Scopus

IEEE ICVISIP 2024 | Kunming, China

Published by IEEE

ISBN: 979-8-3315-4146-0

EI Compendex & Scopus

ICVISIP 2025 | Xi'an, China

Published by IEEE

ISBN: 979-8-3315-5682-2

EI Compendex & Scopus

Submission

- Manuscripts submitted to the conference should be written in English only.
- Manuscripts submitted to the conference should follow the template provided.
- Manuscripts can be submitted in Doc, Docx and PDF format.
- Oral or Poster presentations should be nominated while submitting an abstract.
- The ordinary length is suggested no less than 5 pages, including all figures, tables, references, and appendices. If the paper exceeds 5 pages, the additional pages will be charged at the time of registration.

For paper template, please visit: www.icvisp.org/sub.html

Online Submission link: <https://cmt3.research.microsoft.com/ICVISIP2026>

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